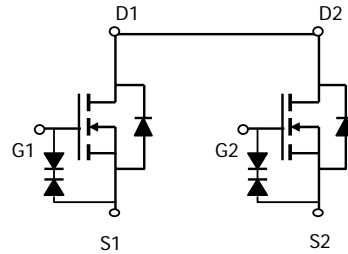
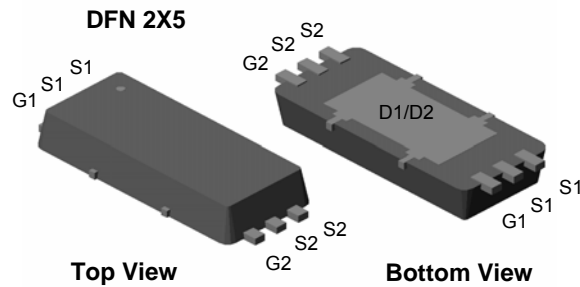


AON5802
Common-Drain Dual N-Channel Enhancement Mode Field Effect Transistor
General Description

The AON5802 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V while retaining a 12V $V_{GS(MAX)}$ rating. It is ESD protected. This device is suitable for use as a uni-directional or bi-directional load switch, facilitated by its common-drain configuration. *Standard Product AON5802 is Pb-free (meets ROHS & Sony 259 specifications).*

Features

$V_{DS} (V) = 30V$
 $I_D = 7.2A (V_{GS} = 4.5V)$
 $R_{DS(ON)} < 20 m\Omega (V_{GS} = 4.5V)$
 $R_{DS(ON)} < 22 m\Omega (V_{GS} = 4.0V)$
 $R_{DS(ON)} < 24 m\Omega (V_{GS} = 3.1V)$
 $R_{DS(ON)} < 30 m\Omega (V_{GS} = 2.5V)$
 ESD Protected


Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 12	
Continuous Drain Current $R_{\theta JA}=75^\circ C/W$	I_D	$T_A=25^\circ C$ 7.2	A
Current $T_A=70^\circ C$		5.6	
Pulsed Drain Current ^B	I_{DM}	65	
Power Dissipation ^A	P_{DSM}	$T_A=25^\circ C$ 1.7	W
$R_{\theta JA}=75^\circ C/W$		$T_A=70^\circ C$ 1.0	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	$t \leq 10s$ 30	40	$^\circ C/W$
Maximum Junction-to-Ambient ^A		Steady-State	61	75
Maximum Junction-to-Lead ^C	$R_{\theta JL}$	4.5	6	$^\circ C/W$

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}$, $V_{GS}=0\text{V}$	30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=24\text{V}$, $V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1	μA
					5	
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 10\text{V}$			10	μA
BV_{GSO}	Gate-Source Breakdown Voltage	$V_{DS}=0\text{V}$, $I_G=\pm 250\mu\text{A}$	± 12			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	0.6	1	1.5	V
$I_{D(ON)}$	On state drain current	$V_{GS}=4.5\text{V}$, $V_{DS}=5\text{V}$	65			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=4.5\text{V}$, $I_D=7.2\text{A}$ $T_J=125^\circ\text{C}$	13	17	20	m Ω
			20	26	30	
		$V_{GS}=4.0\text{V}$, $I_D=4\text{A}$	13	17.2	22	
		$V_{GS}=3.1\text{V}$, $I_D=4\text{A}$	15	19	24	
		$V_{GS}=2.5\text{V}$, $I_D=3\text{A}$	16	22	30	
g_{FS}	Forward Transconductance	$V_{DS}=5\text{V}$, $I_D=7.2\text{A}$		37		S
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}$, $V_{GS}=0\text{V}$	0.5	0.76	0.9	V
I_S	Maximum Body-Diode Continuous Current				4.5	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}$, $V_{DS}=15\text{V}$, $f=1\text{MHz}$		1115		pF
C_{oss}	Output Capacitance			125		pF
C_{rss}	Reverse Transfer Capacitance			100		pF
R_g	Gate resistance	$V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $f=1\text{MHz}$		1.5		Ω
SWITCHING PARAMETERS						
$Q_g(4.5\text{V})$	Total Gate Charge	$V_{GS}=4.5\text{V}$, $V_{DS}=15\text{V}$, $I_D=7.2\text{A}$		10.7		nC
Q_{gs}	Gate Source Charge			2.1		nC
Q_{gd}	Gate Drain Charge			4.3		nC
$t_{D(on)}$	Turn-On Delay Time	$V_{GS}=10\text{V}$, $V_{DS}=15\text{V}$, $R_L=2.1\Omega$, $R_{GEN}=3\Omega$		3.4		ns
t_r	Turn-On Rise Time			11.2		ns
$t_{D(off)}$	Turn-Off Delay Time			27.2		ns
t_f	Turn-Off Fall Time			6.7		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=7.2\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		24.6		ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=7.2\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		12.9		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design. The current rating is based on the steady state thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C: The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

D: The static characteristics in Figures 1 to 6 are obtained using $<300\ \mu\text{s}$ pulses, duty cycle 0.5% max.

E: These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

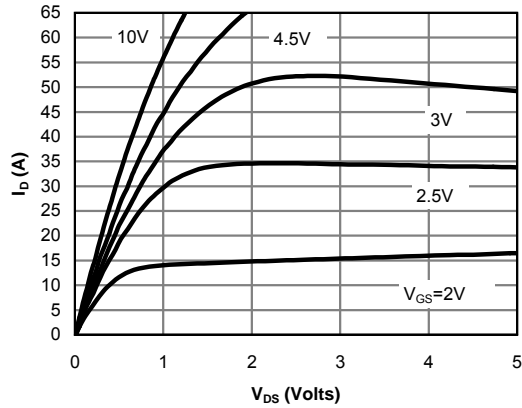


Fig 1: On-Region Characteristics

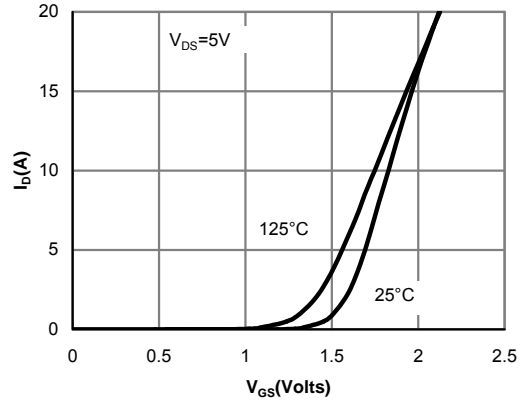


Figure 2: Transfer Characteristics

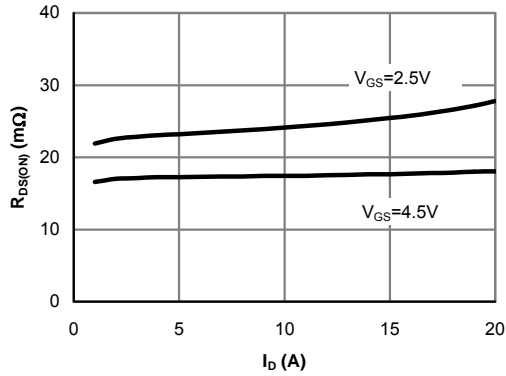


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

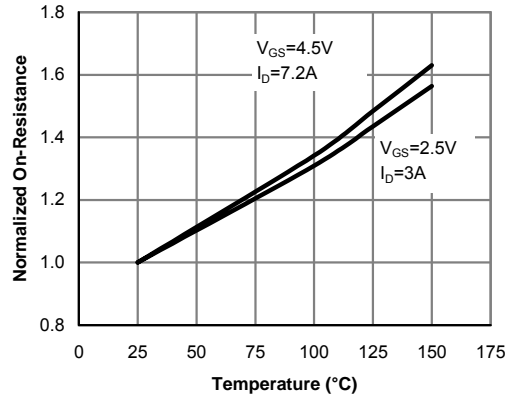


Figure 4: On-Resistance vs. Junction Temperature

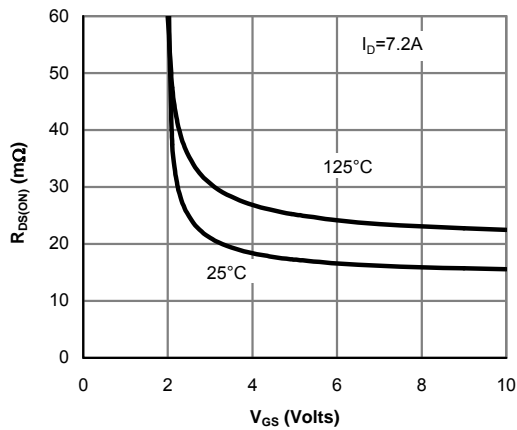


Figure 5: On-Resistance vs. Gate-Source Voltage

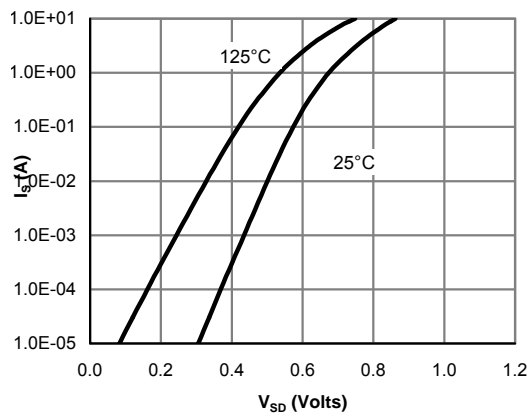


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

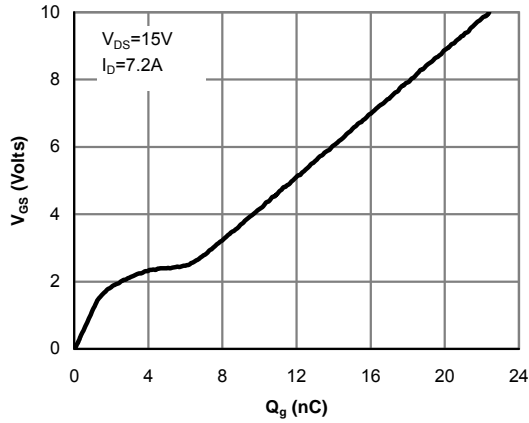


Figure 7: Gate-Charge Characteristics

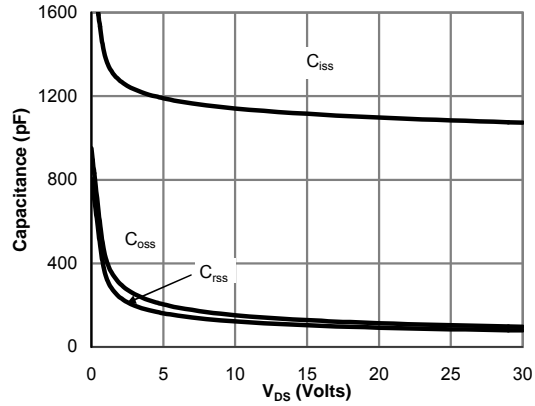


Figure 8: Capacitance Characteristics

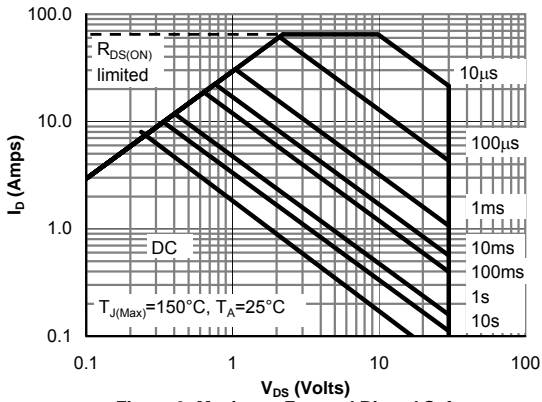


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

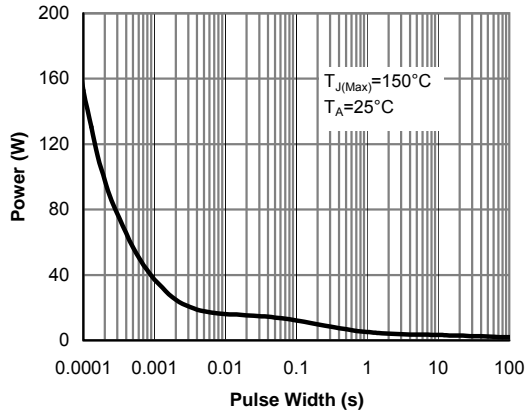


Figure 10: Single Pulse Power Rating Junction-to-Case (Note E)

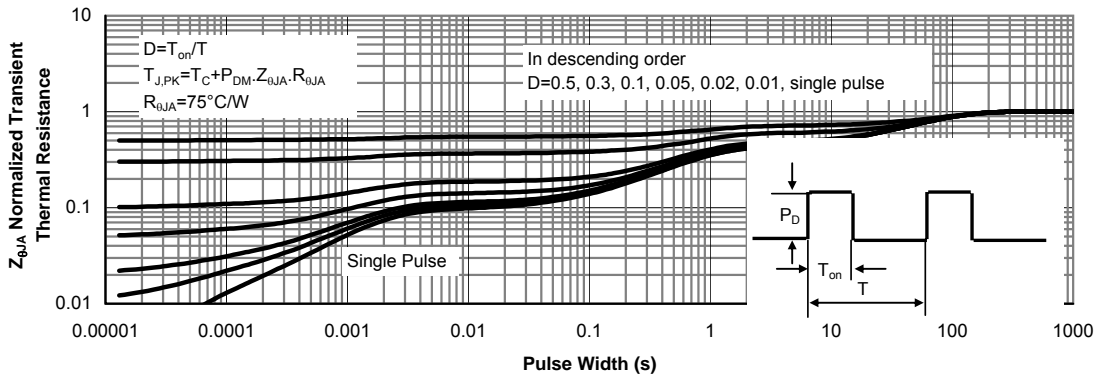


Figure 11: Normalized Maximum Transient Thermal Impedance (Note E)